

REBO-9Twin

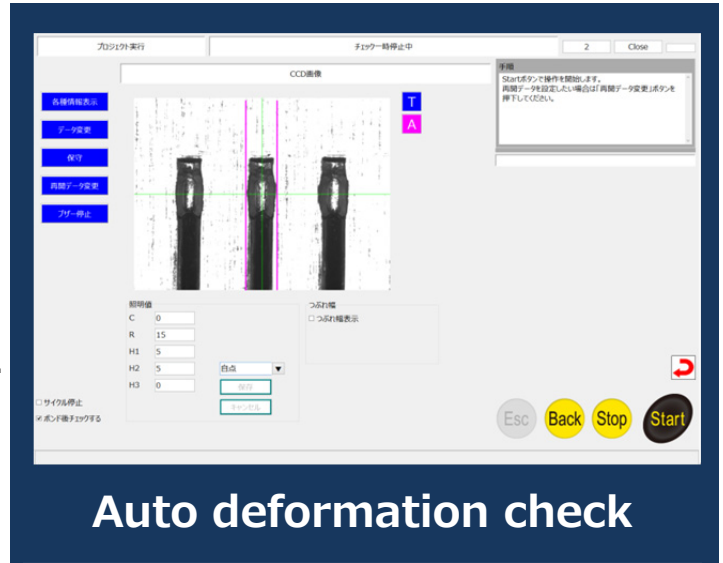
Rotary Head Wire Bonder



High performance wire bonder

REBO-9Twin NEW model available

- ◆ Y direction of bonding area became 70mm, easily applicable to wide product.
- ◆ Bonder became approx.24% more compact (Compared with 2 single head connected) .
- ◆ Equipped with Touch-panel for easy operation.
- ◆ Bonder Exchange Kit enables REBO-9T to handle large, medium, small wire and ribbon .



REBO-9Twin MAJOR SPECIFICATION

	REBO-9Twin				
Wire	Small wire	Medium wire	Large wire	ribbon	Cu wire
Wire/Ribbon size	25~50μm	75~150μm	100~500μm	W:0.5~2.0mm T:0.1~0.3mm	200~500μm
Wire material	Aluminum				Copper
Ultrasonic frequency	120kHz	110kHz		80kHz	
Bonding area	X : 130 × Y : 160 mm Standard				
Basic os	Windows 8※				
Wave monitor Logging	Transducer current & voltage, power, sink depth, phase, and voltage controlled oscillation. *VCO is not available for small wire.				
Data making support	Offline data making software REBOnWin				
Product size	Approx. 1725 (W) × 1225 (D) × 1630 (H) mm (Signal tower and other projectiles not included.)				
Mass weight	Approx. 980 kg				
Power	Single phase 200V~240V 50/60Hz				


※Windows is a registered trademark of United States Microsoft Corporation.



Caution: Please read operation manual carefully before using.

The specification and outer dimensions are subject to change without prior notice for improvement.

<http://www.cho-onpa.co.jp/> Latest information available.

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